



Description

The DMC4029SK4 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO-252-4L

$V_{DS} = 40V$ $I_D = 20A$

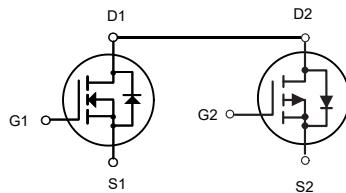
$R_{DS(ON)} < 24m\Omega$ @ $V_{GS}=10V$

$V_{DS} = -40V$ $I_D = -20A$

$R_{DS(ON)} < 38m\Omega$ @ $V_{GS}=-10V$

Application

Wireless charging



N-Channel MOSFET

P-Channel MOSFET

Boost driver

Brushless motor

Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|------------|-----------|------------|----------|
| DMC4029SK4 | TO-252-4L | HXY MOSFET | 2500 |

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

| Symbol | Parameter | Rating | | Units |
|------------------------|--|------------|------------|--------------|
| | | N-Channel | P-Channel | |
| V_{DS} | Drain-Source Voltage | 40 | -40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | ± 20 | V |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 20 | -20 | A |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 16.5 | -16.5 | A |
| I_{DM} | Pulsed Drain Current ² | 40 | -40 | A |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation ⁴ | 40 | 40 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | -55 to 150 | $^\circ C$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | 62 | | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | 3.1 | | $^\circ C/W$ |

**N-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)**

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|----------------------------|--|-----|------|-----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 40 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 1 | 1.5 | 2.0 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$ | - | 18 | 24 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$ | - | 26 | 37 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$ | | 15 | - | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 1500 | - | PF |
| Output Capacitance | C_{oss} | | - | 215 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 135 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=20\text{V}, R_{\text{L}}=2\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$ | - | 4 | - | nS |
| Turn-on Rise Time | t_{r} | | - | 11.5 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 18 | - | nS |
| Turn-Off Fall Time | t_{f} | | - | 5.6 | - | nS |
| Total Gate Charge | Q_{g} | $V_{\text{DS}}=20\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}$ | - | 24 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 4 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 3.5 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{s}}=10\text{A}$ | - | 0.8 | 1.2 | V |

**P-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)**

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|----------------------------|--|------|------|----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$ | -40 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | -1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ±100 | nA |
| On Characteristics ^(Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$ | -1.0 | -1.5 | -2.0 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-7\text{A}$ | - | 33 | 38 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-4\text{A}$ | - | 37 | 49 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-7\text{A}$ | - | 15 | - | S |
| Dynamic Characteristics ^(Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 1225 | - | PF |
| Output Capacitance | C_{oss} | | - | 190 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 120 | - | PF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=-20\text{V}, R_{\text{L}}=2.3\Omega$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=6\Omega$ | - | 10 | - | nS |
| Turn-on Rise Time | t_{r} | | - | 15 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 30 | - | nS |
| Turn-Off Fall Time | t_{f} | | - | 18 | - | nS |
| Total Gate Charge | Q_{g} | $V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-7\text{A}$ $V_{\text{GS}}=-10\text{V}$ | - | 21 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 3.5 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 3.0 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ^(Note 3) | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{S}}=-14\text{A}$ | - | - | -1.2 | V |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production



N- Channel Typical Electrical and Thermal Characteristics (Curves)

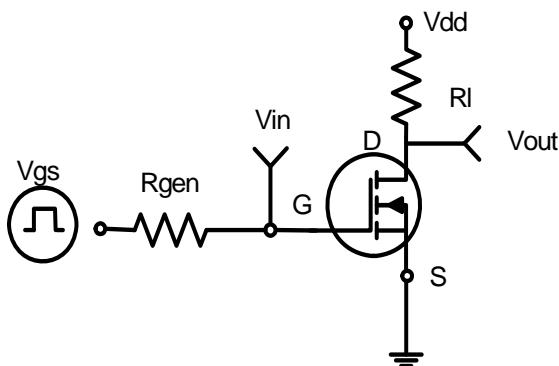


Figure 1:Switching Test Circuit

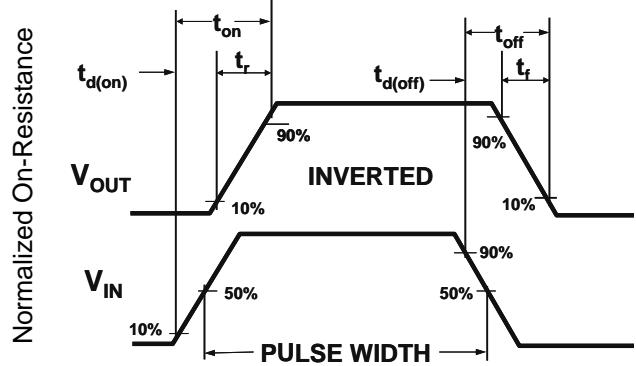


Figure 2:Switching Waveforms

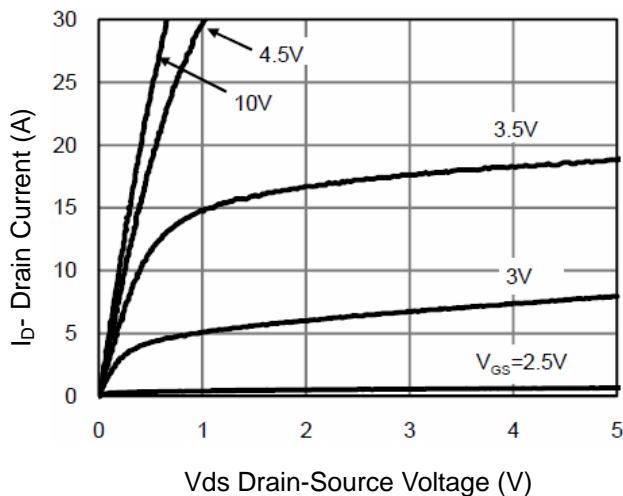


Figure 3 Output Characteristics

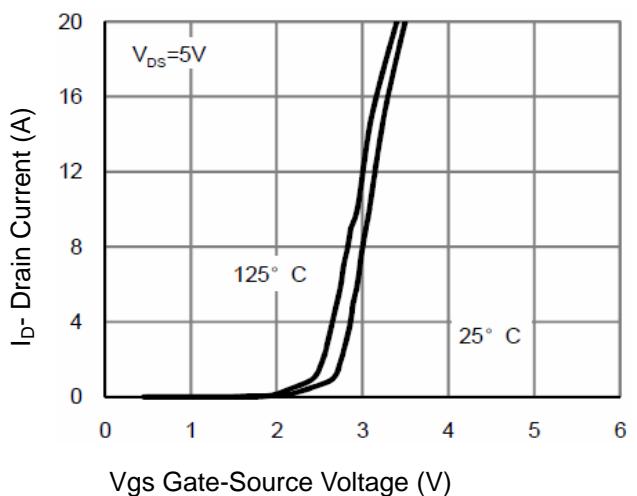


Figure 4 Transfer Characteristics

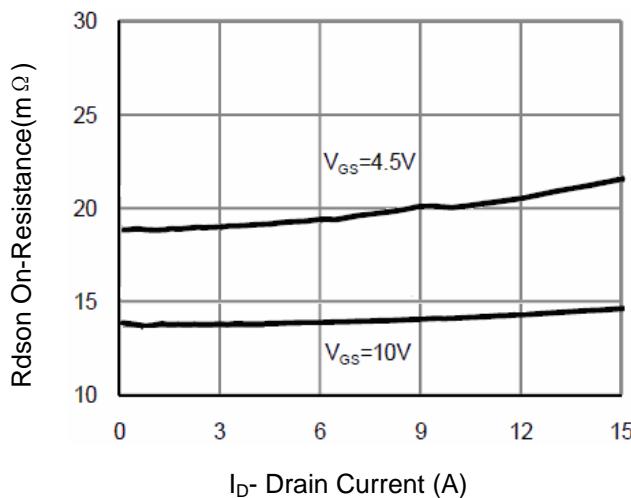


Figure 5 Drain-Source On-Resistance

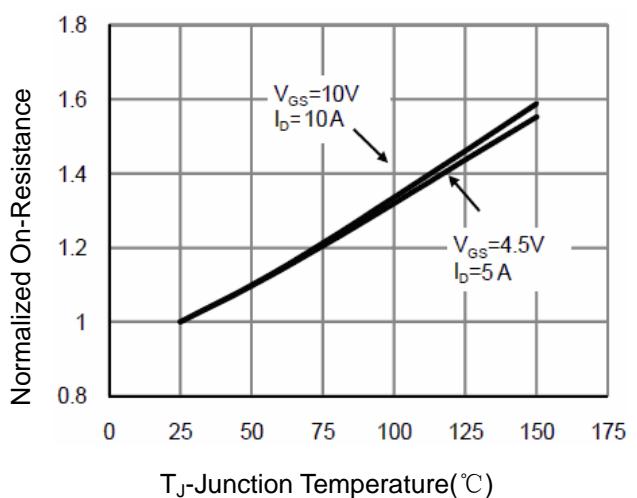
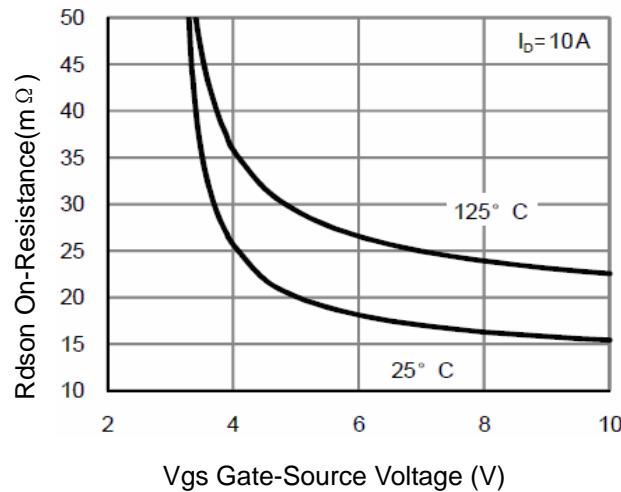
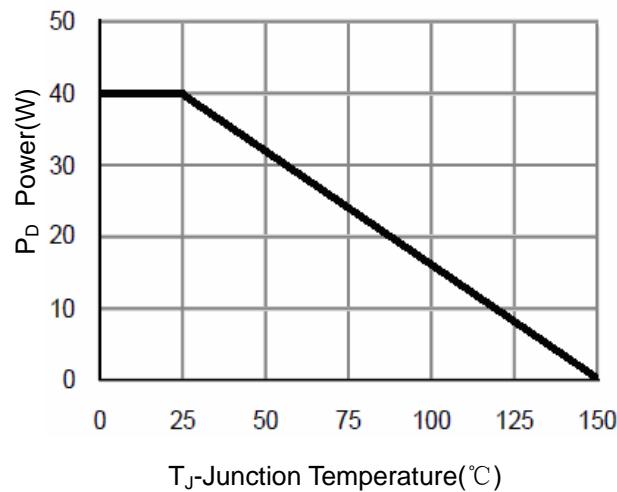


Figure 6 Drain-Source On-Resistance



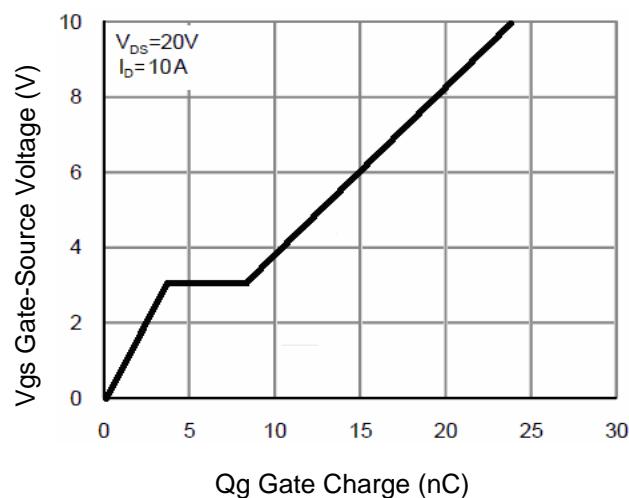
V_{GS} Gate-Source Voltage (V)

Figure 7 Rdson vs Vgs



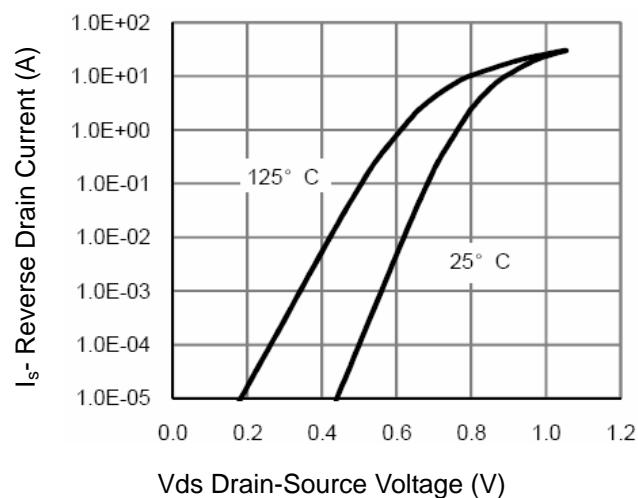
T_J -Junction Temperature (°C)

Figure 8 Power Dissipation



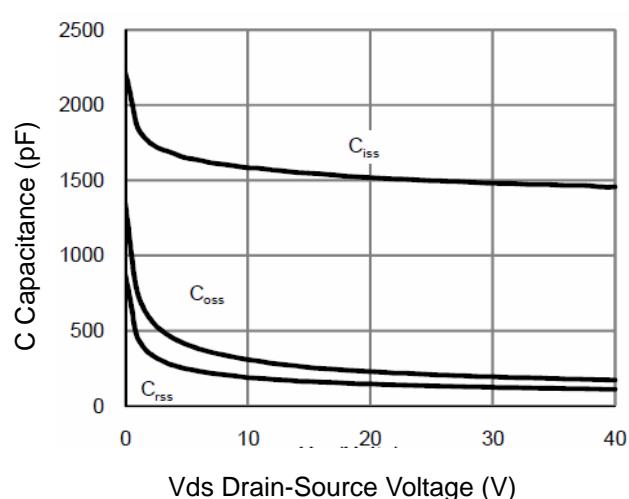
Q_g Gate Charge (nC)

Figure 9 Gate Charge



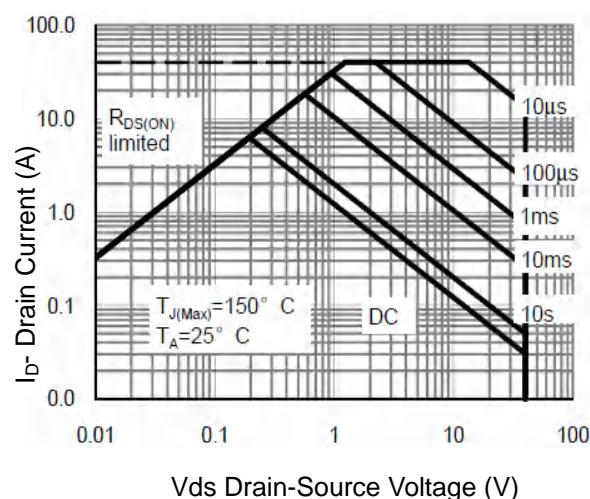
V_{DS} Drain-Source Voltage (V)

Figure 10 Source- Drain Diode Forward



V_{DS} Drain-Source Voltage (V)

Figure 11 Capacitance vs Vds



V_{DS} Drain-Source Voltage (V)

Figure 12 Safe Operation Area

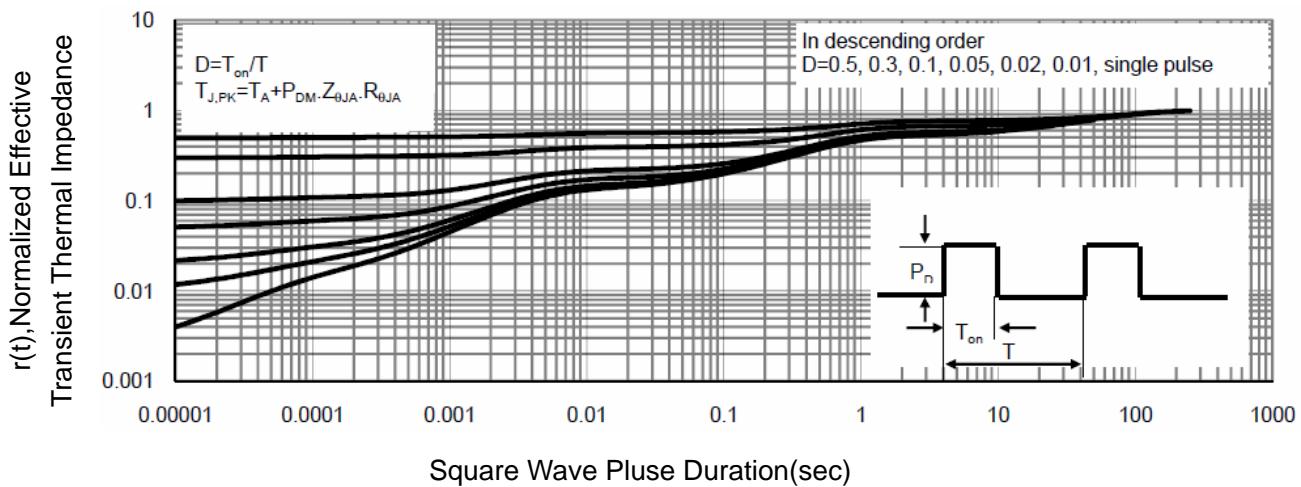


Figure 13 Normalized Maximum Transient Thermal Impedance



P- Channel Typical Electrical and Thermal Characteristics (Curves)

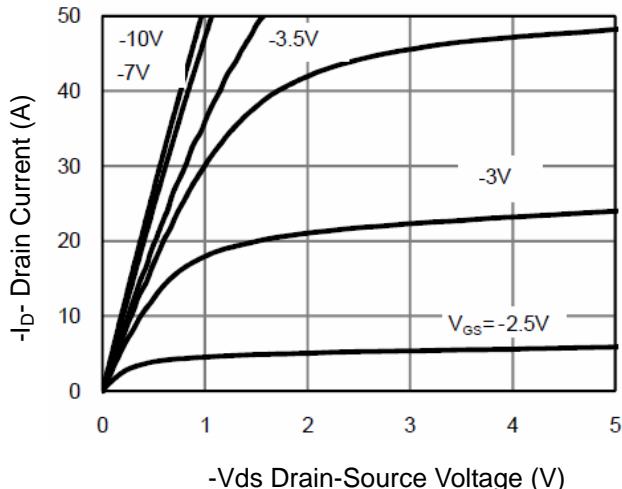


Figure 1 Output Characteristics

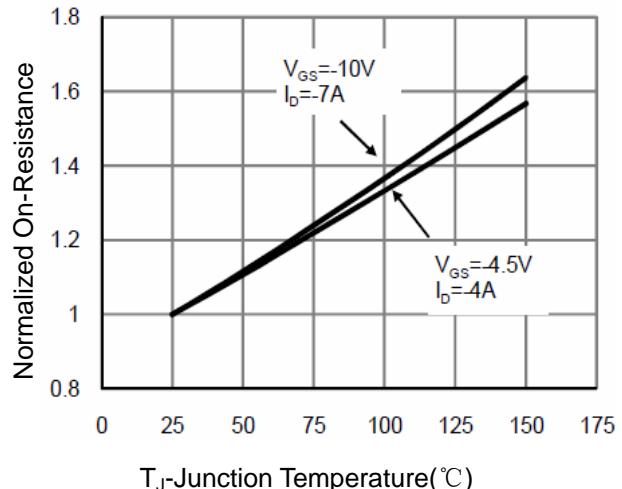


Figure 4 $R_{DS(on)}$ -Junction Temperature

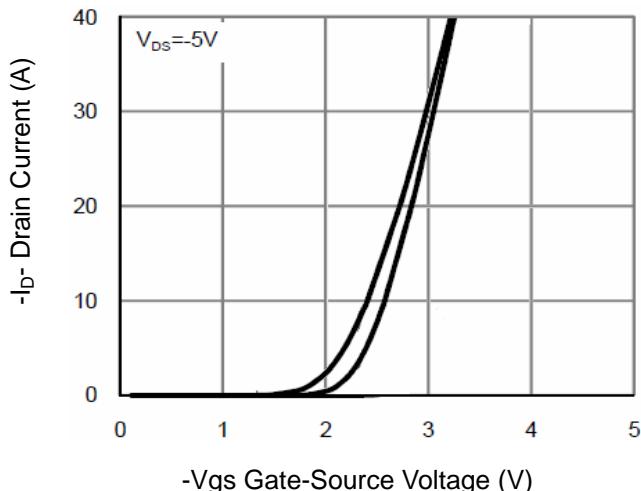


Figure 2 Transfer Characteristics

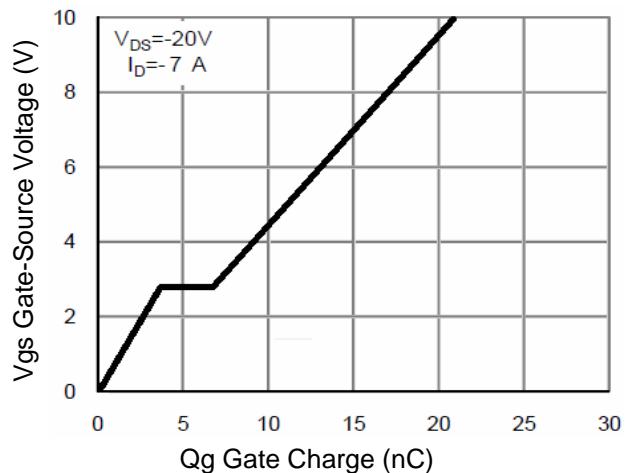


Figure 5 Gate Charge

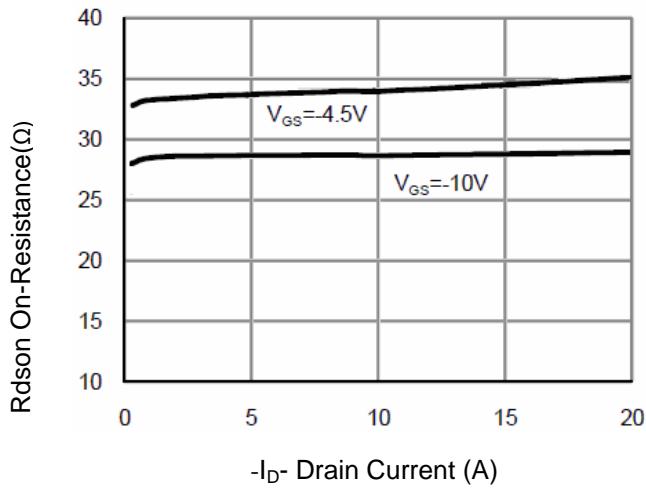


Figure 3 $R_{DS(on)}$ - Drain Current

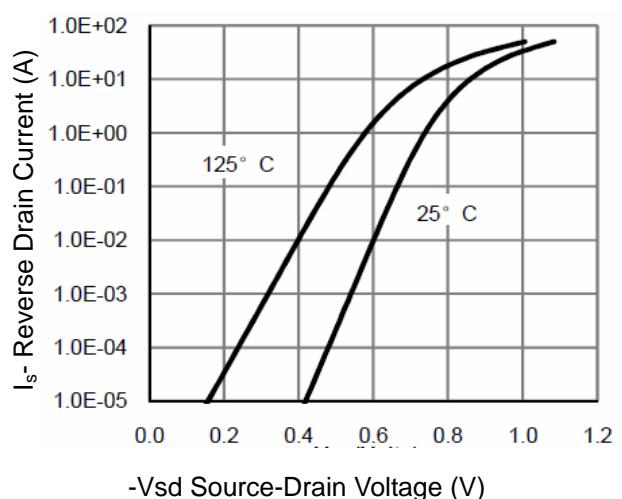


Figure 6 Source- Drain Diode Forward

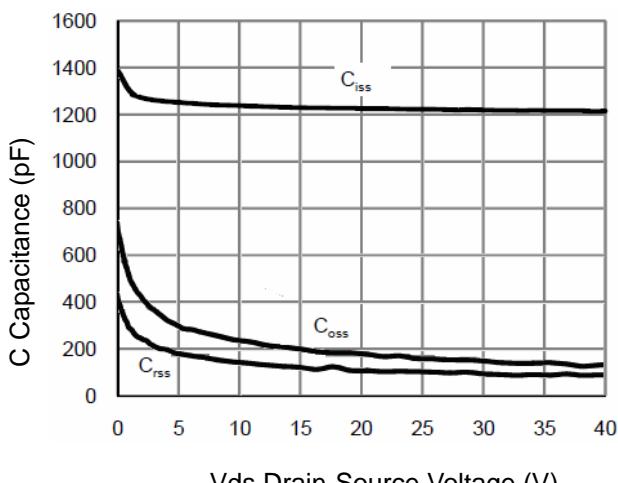


Figure 7 Capacitance vs Vds

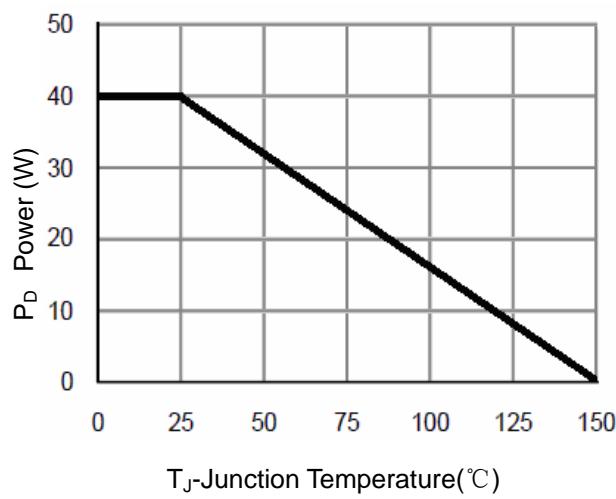


Figure 9 Power Dissipation

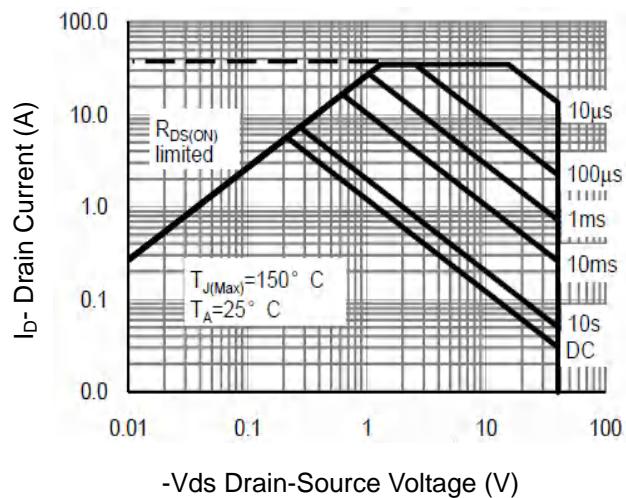


Figure 8 Safe Operation Area

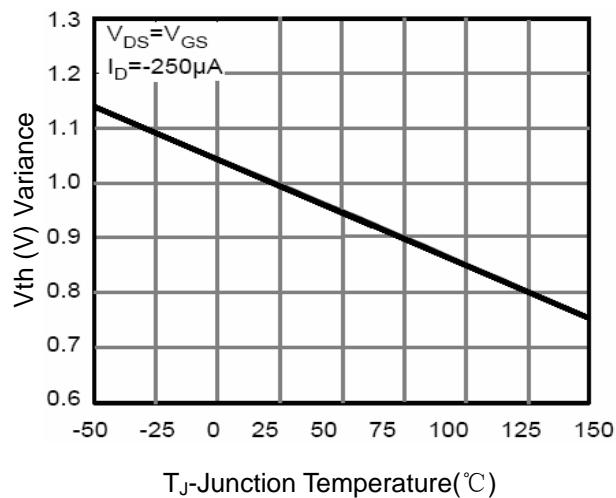


Figure 10 $V_{GS(th)}$ vs Junction Temperature

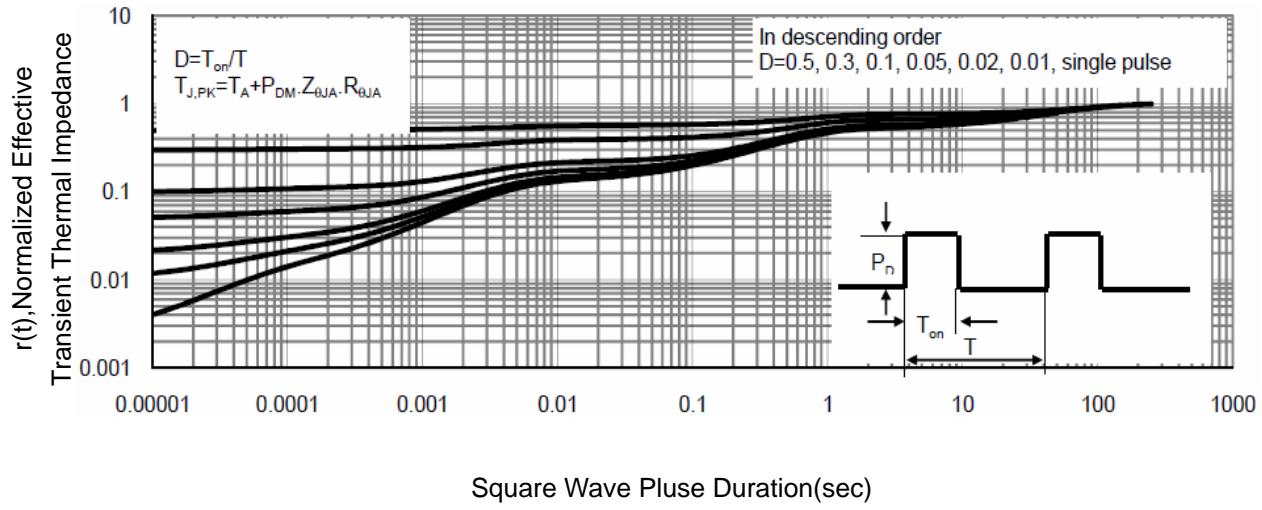
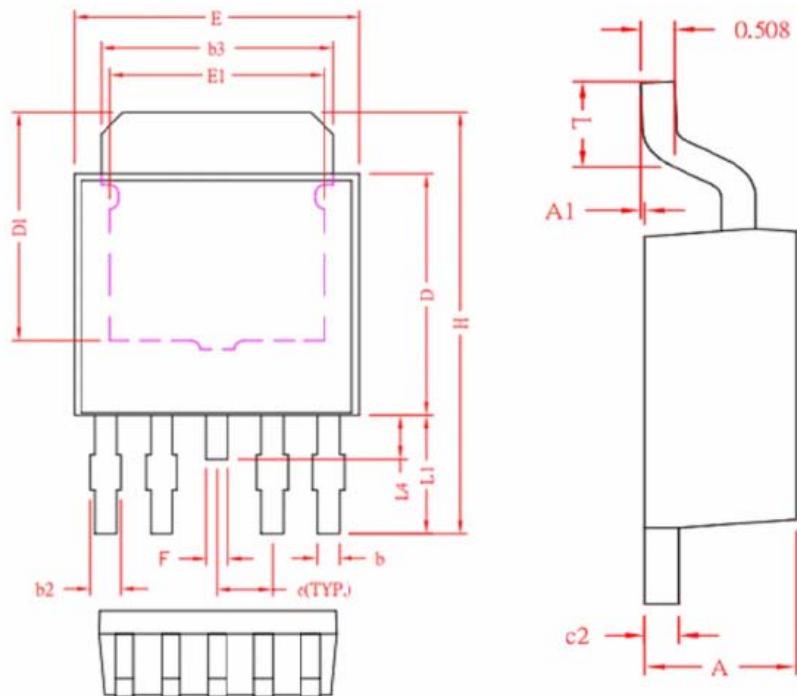


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-252-4L Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

| SYMBOL | MIN | NOM | MAX |
|--------|-----------|------|-------|
| A | 2.20 | 2.30 | 2.40 |
| A1 | 0 | 0.08 | 0.15 |
| b | 0.45 | 0.53 | 0.60 |
| b2 | 0.50 | 0.65 | 0.80 |
| b3 | 5.20 | 5.35 | 5.50 |
| c2 | 0.45 | 0.50 | 0.55 |
| D | 5.40 | 5.60 | 5.80 |
| D1 | 4.57 | - | - |
| E | 6.40 | 6.60 | 6.80 |
| E1 | 3.81 | - | - |
| e | 1.27 REF. | | |
| F | 0.40 | 0.50 | 0.60 |
| H | 9.40 | 9.80 | 10.20 |
| L | 1.40 | 1.59 | 1.77 |
| L1 | 2.40 | 2.70 | 3.00 |
| L4 | 0.80 | 1.00 | 1.20 |



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